

**RECEIVED
CENTRAL FAX CENTER****Patent****SEP 09 2005****Customer No.: 31561****Docket No.: 10788-US-PA****Application No.: 10/709,923****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Huang et al.

Application No. : 10/709,923

Filed : 2004/6/7

For : FLIP-CHIP PACKAGE SUBSTRATE AND FLIP-CHIP
BONDING PROCESS THEREOF

Art Unit : 2826

Examiner : Williams, Alexander O.

TRANSMITTAL LETTER**002-1-571-273-8300****(Via fax : 1+4 pages)**Assistant Commissioner for Patents
Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated August 11, 2005(Paper No.: 20050804),
please find the Response to Office Action, in 4 pages.

I believe that no fee is incurred. However, the Commissioner is authorized to charge
any fees required in connection with the filing of this paper to account No. 50-2620
(Order No.: 10788-US-PA).

Thank you for your assistance in the subject matter. If you have any questions,
please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property OfficeDate : Sept. 9, 2005By : Belinda Lee
Belinda Lee
Registration No.: 46,863**Please send future correspondence to:****7F. -1, No. 100, Roosevelt Rd.,****Sec. 2, Taipei 100, Taiwan, R.O.C.****Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234****E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw**

